

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	274	semiconductor and (back\$2grinding)	USPAT	OR	OFF	2006/10/05 11:59
L2	489	semiconductor and (back\$2grinding)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/05 11:59

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	10246	(semiconductor adj (wafer or chip or die or ic)) and (protect\$4 near4 (sheet or layer or structure))	USPAT	OR	ON	2006/10/05 09:43
L2	4063	(semiconductor adj (wafer or chip or die or ic)) and (protect\$4 adj1 (sheet or layer or structure))	USPAT	OR	ON	2006/10/05 09:45
L3	2447	(semiconductor adj wafer) and (protect\$4 adj1 (sheet or layer or structure))	USPAT	OR	ON	2006/10/05 10:44
L4	2352	(semiconductor adj wafer) and (protect\$4 adj1 (sheet or layer or structure))	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/05 10:44